Special Issue

3D-Printed Implants: Design, Manufacture, Simulation and Applications

Message from the Guest Editors

We are pleased to invite you to publish your original research findings in this Special Issue, titled "3D-Printed Implants: Design, manufacture, simulation and applications". The Special Issue aims to explore the advancements, challenges, and applications in the field of 3D-printed implants, with a focus on design, manufacturing, simulation, and applications. This Special Issue also hopes to provide a holistic understanding of the state of the art in this rapidly evolving research area. In this Special Issue, original research articles and reviews are welcome. Research areas may include (but are not limited to) the following topics:

- 3D printing technology;
- Additive manufacturing;
- Point-of-care manufacturing;
- Design of biocompatible and biodegradable materials;
- Computational simulation;
- In silico studies:
- Medical implants.

We look forward to receiving your contributions.

Guest Editors

Dr. Michael I. Okereke

Prof. Dr. Dennis Douroumis

Dr. Mahdi Bodaqhi

Deadline for manuscript submissions

closed (1 August 2024)



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About the Journal

Message from the Editor-in-Chief

You are invited to contribute research articles or comprehensive reviews for consideration and publication in *Micromachines* (ISSN 2072-666X). *Micromachines* is published in the open access format. Research articles, reviews and other contents are released on the internet immediately after acceptance. The scientific community and the general public have unlimited free access to the content as soon as it is published. As an open access journal, *Micromachines* is supported by the authors or their institutes by payment of article processing charges (APC) for accepted papers. We are pleased to welcome you as our authors.

Editor-in-Chief

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